

Electronic Patent Application Fee Transmittal

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| Application Number: | 10588927 |
| Filing Date: | |
| Title of Invention: | Semiconductor Package with Perforated Substrate |
| First Named Inventor/Applicant Name: | Irwin Aberin |
| Filer: | Steven Edward Dicke/Cindy Schlotz |
| Attorney Docket Number: | 1431.168.101/FIN581PCT/US |

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 1 month with \$0 paid | 1251 | 1 | 120 | 120 |

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